

Product Information

Lead-free electronic solder FELDER-ISO-Tin® „Sn99Ag+REFILL“

Lead-free refill solder for selective and wave soldering units, RoHS conformity acc. 2011/65/EU
Sn99,6Ag0,3NiGe acc. to Fuji-Pat. No. DE19816671C2, US6179.935, JP3296289
Sn99,6Ag0,3Ni (Ge) according to DIN EN 9452:2014

Item-No.: 551282

All information about our products is the result of our long standing experience which we would like to pass on to our customers as application support. However, as we do not have any influence on the application of the works carried out with our products, please see the warranty claims in our conditions of sale because our liability is limited.

This product information does not constitute warranted properties.

Application

In order to compensate the entry of copper into the lead-free alloy Sn99Ag+ in wave soldering and selective soldering units we recommend Sn99Ag+ Refill. Hereto a regular control of the solder bath is unavoidable.

Properties

As most of the PCBs and components have copper-plated conducting paths and connections copper is flushed into the solder bath by the soldering process. In fact Sn99Ag+ has a lower dealloying quote of copper as other lead-free solders, nevertheless a copper level compensation is necessary.

Alloy: Sn99,6Ag0,3NiGe
 Melting point: reduces in the solder bath to 217 – 227 ° C!

Impurities / Tolerances

Sn99Ag+

Element	Ag	Al	As	Bi	Cd	Cu	Fe
content (%)	0,3±0,1	0,001	0,03	0,06	0,002	0,7±0,2	0,02
Element	Ge	Ni	Pb	Sb	Sn	Zn	
content (%)	0,01 - 0,015	0,06±0,02	0,07	0,1	Rest	0,001	

Delivery Forms

400 g - rods, 330 x 20 x 10 mm,
 3,5 kg – blocks with hanging hole 545 x 47 x 20 mm.
 Also deliverable as massive wire on spools and wire cuts for first filling.
 Other alloys are included in our standard delivery program.

Storage

Stored at constant indoor climate durable for an unlimited period!